Surface Mount Schottky Power Rectifier

SMB Power Surface Mount Package

... employing the Schottky Barrier principle in a metal-to-silicon power rectifier. Features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency switching power supplies; free wheeling diodes and polarity protection diodes.

- Compact Package with J-Bend Leads Ideal for Automated Handling
- Highly Stable Oxide Passivated Junction
- Guardring for Over–Voltage Protection
- Low Forward Voltage Drop
- Pb–Free Package May be Available. The G–Suffix Denotes a Pb–Free Lead Finish

Mechanical Characteristics:

- Case: Molded Epoxy
- Epoxy Meets UL94, VO at 1/8"
- Weight: 95 mg (approximately)
- Maximum Temperature of 260°C / 10 Seconds for Soldering
- Cathode Polarity Band
- Available in 12 mm Tape, 2500 Units per 13 inch Reel, Add "T3" Suffix to Part Number
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Marking: BKJL

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	40	V
Average Rectified Forward Current (At Rated V _R , T _C = 103°C)	ΙO	2.0	А
Peak Repetitive Forward Current (At Rated V _R , Square Wave, 20 kHz, T _C = 104°C)	IFRM	4.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	IFSM	70	A
Storage/Operating Case Temperature	T _{stg} , T _C	-55 to +150	°C
Operating Junction Temperature	ТJ	-55 to +125	°C
Voltage Rate of Change (Rated V _R , T _J = 25° C)	dv/dt	10,000	V/µs



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SCHOTTKY BARRIER RECTIFIER 2.0 AMPERES 40 VOLTS



SMB CASE 403A PLASTIC

MARKING DIAGRAM



BKJL = Device Code

ORDERING INFORMATION

Device	Package	Shipping [†]
MBRS2040LT3	SMB	2500/Tape & Reel
MBRS2040LT3G	SMB (Pb–Free)	2500/Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



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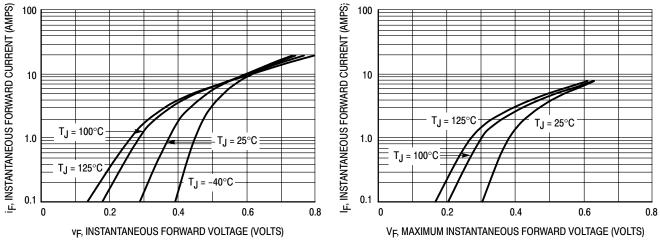
THERMAL CHARACTERISTICS

Characteristic		Symbol	Value		Unit
Thermal Resistance — Junction-to-Lead (Note 1.) Thermal Resistance — Junction-to-Ambient (Note 2.)		R _{θJL} R _{θJA}	22.5 78		°C/W
ELECTRICAL CHARACTERISTICS					
Maximum Instantaneous Forward Voltage (Note 3.)		VF	TJ = 25°C	TJ = 125°C	Volts
see Figure 2	(I _F = 2.0 A) (I _F = 4.0 A)		0.43 0.50	0.34 0.45	
Maximum Instantaneous Reverse Current (Note 3.)		IR	TJ = 25°C	TJ = 100°C	mA
	(V _R = 40 V)		0.8	20	
see Figure 4	(V _R = 20 V)		0.1	6.0	

 1. Minimum pad size (0.108 X 0.085 inch) for each lead on FR4 board.

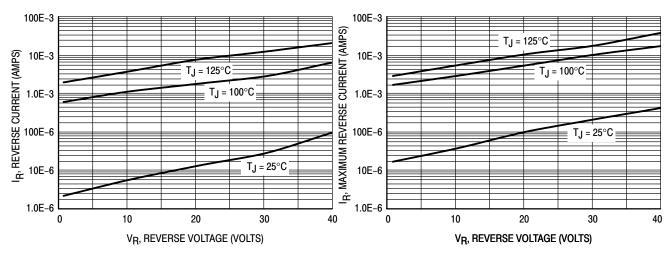
 2. 1 inch square pad size (1 x 0.5 inch for each lead) on FR4 board.

 3. Pulse Test: Pulse Width \leq 250 µs, Duty Cycle \leq 2.0%.



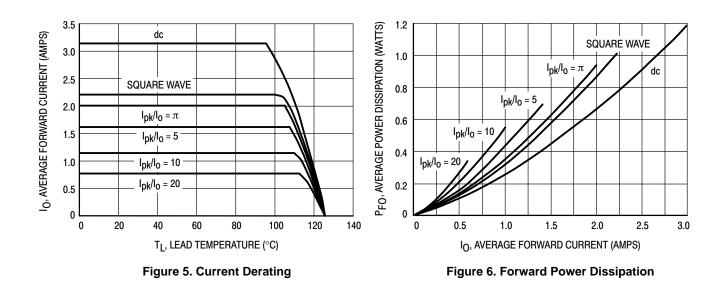


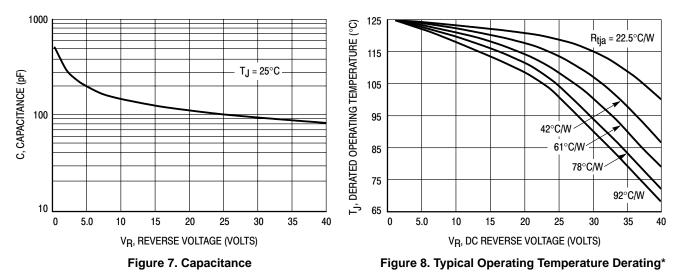








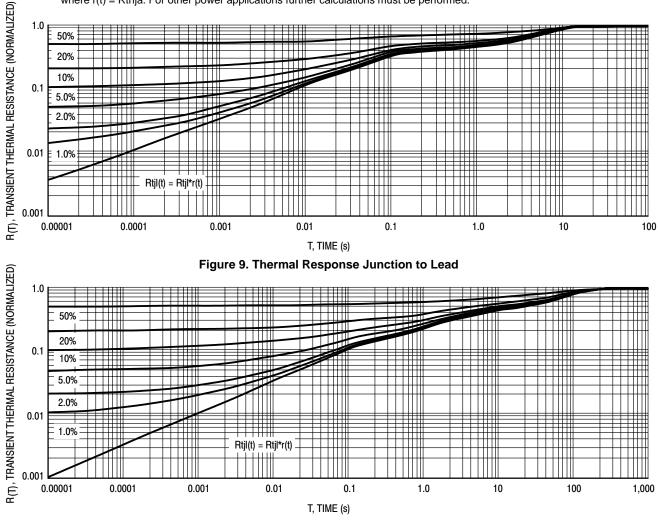




* Reverse power dissipation and the possibility of thermal runaway must be considered when operating this device under any reverse voltage conditions. Calculations of T_J therefore must include forward and reverse power effects. The allowable operating T_J may be calculated from the equation: $T_J = T_{Jmax} - r(t)(Pf + Pr)$ where

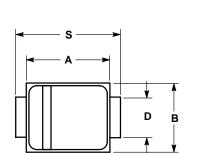
- r(t) = thermal impedance under given conditions,
- Pf = forward power dissipation, and
- Pr = reverse power dissipation

This graph displays the derated allowable T_J due to reverse bias under DC conditions only and is calculated as $T_J = T_{Jmax} - r(t)Pr$, where r(t) = Rthja. For other power applications further calculations must be performed.

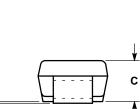




PACKAGE DIMENSIONS

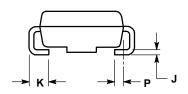


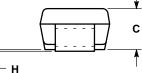




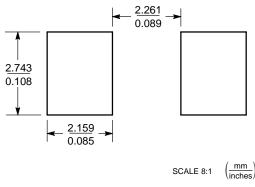
- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. D DIMENSION SHALL BE MEASURED WITHIN DIMENSION P.

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.160	0.180	4.06	4.57	
В	0.130	0.150	3.30	3.81	
С	0.075	0.095	1.90	2.41	
D	0.077	0.083	1.96	2.11	
н	0.0020	0.0060	0.051	0.152	
J	0.006	0.012	0.15	0.30	
K	0.030	0.050	0.76	1.27	
Р	0.020 REF		0.51 REF		
S	0.205	0.220	5.21	5.59	





SOLDERING FOOTPRINT*



SMB

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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